

EAST Search History

EAST Search History (Prior Art)

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|------|--|---|------------------|---------|---------------------|
| S1 | 218 | 337/333.ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | AND | ON | 2009/09/03 17:30 |
| S2 | 8 | (adriana near2 sartor).in. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | AND | ON | 2009/09/03 17:30 |
| S3 | 23 | elettrotec.as. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | AND | ON | 2009/09/03 17:33 |
| S4 | 8 | S2 S3 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | AND | ON | 2009/09/03 17:35 |
| S5 | 0 | 337/380.ccls. ((bimetal\$3 or (bi near2 metal \$3)) (thermostat \$3 or switch) contact relay (feet with (base or bottom)) ((PCB or board or substrate) with (trac\$3 or wir\$3 or pattern))) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | AND | ON | 2009/09/03 17:37 |

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| S6 | 0 | 337/372.ccls. ((bimetal\$3 or (bi near2 metal \$3)) (thermostat \$3 or switch) contact relay (feet with (base or bottom)) ((PCB or board or substrate) with (trac\$3 or wir\$3 or pattern))) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | AND | ON | 2009/09/03 17:37 |
| S7 | 0 | 337/107.ccls. ((bimetal\$3 or (bi near2 metal \$3)) (thermostat \$3 or switch) contact relay (feet with (base or bottom)) ((PCB or board or substrate) with (trac\$3 or wir\$3 or pattern))) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | AND | ON | 2009/09/03 17:37 |
| S8 | 0 | 337/16.ccls. ((bimetal\$3 or (bi near2 metal \$3)) (thermostat \$3 or switch) contact relay (feet with (base or bottom)) ((PCB or board or substrate) with (trac\$3 or wir\$3 or pattern))) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | AND | ON | 2009/09/03 17:37 |

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| S9 | 0 | 337/3.ccls. ((bimetal\$3 or (bi near2 metal \$3)) (thermostat \$3 or switch) contact relay (feet with (base or bottom)) ((PCB or board or substrate) with (trac\$3 or wir\$3 or pattern))) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | AND | ON | 2009/09/03 17:38 |
| S10 | 0 | 337/13.ccls. ((bimetal\$3 or (bi near2 metal \$3)) (thermostat \$3 or switch) contact relay (feet with (base or bottom)) ((PCB or board or substrate) with (trac\$3 or wir\$3 or pattern))) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | AND | ON | 2009/09/03 17:38 |
| S11 | 0 | 337/20.ccls. ((bimetal\$3 or (bi near2 metal \$3)) (thermostat \$3 or switch) contact relay (feet with (base or bottom)) ((PCB or board or substrate) with (trac\$3 or wir\$3 or pattern))) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | AND | ON | 2009/09/03 17:38 |

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| S12 | 0 | 337/34.ccls. ((bimetal\$3 or (bi near2 metal \$3)) (thermostat \$3 or switch) contact relay (feet with (base or bottom)) ((PCB or board or substrate) with (trac\$3 or wir\$3 or pattern))) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | AND | ON | 2009/09/03 17:38 |
| S13 | 0 | 337/36.ccls. ((bimetal\$3 or (bi near2 metal \$3)) (thermostat \$3 or switch) contact relay (feet with (base or bottom)) ((PCB or board or substrate) with (trac\$3 or wir\$3 or pattern))) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | AND | ON | 2009/09/03 17:38 |
| S14 | 0 | 361/99.ccls. ((bimetal\$3 or (bi near2 metal \$3)) (thermostat \$3 or switch) contact relay (feet with (base or bottom)) ((PCB or board or substrate) with (trac\$3 or wir\$3 or pattern))) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | AND | ON | 2009/09/03 17:39 |

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| S15 | 0 | 361/626.ccls. ((bimetal\$3 or (bi near2 metal \$3)) (thermostat \$3 or switch) contact relay (feet with (base or bottom)) ((PCB or board or substrate) with (trac\$3 or wir\$3 or pattern))) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | AND | ON | 2009/09/03 17:39 |
| S16 | 0 | "361"/\$.ccls. ((bimetal\$3 or (bi near2 metal \$3)) (thermostat \$3 or switch) contact relay (feet with (base or bottom)) ((PCB or board or substrate) with (trac\$3 or wir\$3 or pattern))) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | AND | ON | 2009/09/03 17:39 |
| S17 | 0 | "337"/\$.ccls. ((bimetal\$3 or (bi near2 metal \$3)) (thermostat \$3 or switch) contact relay (feet with (base or bottom)) ((PCB or board or substrate) with (trac\$3 or wir\$3 or pattern))) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | AND | ON | 2009/09/03 17:39 |

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|-----|-----|--|---|-----|----|------------------|
| S18 | 16 | ((bimetal\$3 or (bi near2 metal \$3)) (thermostat \$3 or switch) contact relay (feet with (base or bottom)) ((PCB or board or substrate) with (trac\$3 or wir\$3 or pattern))) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | AND | ON | 2009/09/03 17:39 |
| S19 | 16 | "337"/\$.ccls. ((bimetal\$3 or (bi near2 metal \$3)) (thermostat \$3 or switch) relay ((PCB or board or substrate) with (trac\$3 or wir\$3 or pattern))) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | AND | ON | 2009/09/03 18:01 |
| S20 | 31 | "361"/\$.ccls. ((bimetal\$3 or (bi near2 metal \$3)) (thermostat \$3 or switch) relay ((PCB or board or substrate) with (trac\$3 or wir\$3 or pattern))) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | AND | ON | 2009/09/03 18:10 |
| S21 | 252 | ((bimetal\$3 or (bi near2 metal \$3)) (thermostat \$3 or switch) relay ((PCB or board or substrate) with (trac\$3 or wir\$3 or pattern))) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | AND | ON | 2009/09/03 18:12 |

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| S22 | 0 | 29/623.ccls. ((bimetal\$3 or (bi near2 metal \$3)) (thermostat \$3 or switch) relay ((PCB or board or substrate) with (trac\$3 or wir\$3 or pattern))) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | AND | ON | 2009/09/03 18:16 |
| S23 | 2 | "29"/\$.ccls. ((bimetal\$3 or (bi near2 metal \$3)) (thermostat \$3 or switch) relay ((PCB or board or substrate) with (trac\$3 or wir\$3 or pattern))) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | AND | ON | 2009/09/03 18:23 |
| S24 | 0 | 439/620.29.ccls. ((bimetal\$3 or (bi near2 metal \$3)) (thermostat \$3 or switch) relay ((PCB or board or substrate) with (trac\$3 or wir\$3 or pattern))) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | AND | ON | 2009/09/03 18:23 |
| S25 | 0 | 439/620.27.ccls. ((bimetal\$3 or (bi near2 metal \$3)) (thermostat \$3 or switch) relay ((PCB or board or substrate) with (trac\$3 or wir\$3 or pattern))) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | AND | ON | 2009/09/03 18:23 |
| S26 | 0 | 439/620.26.ccls. ((bimetal\$3 or (bi near2 metal \$3)) (thermostat \$3 or switch) relay ((PCB or board or substrate) with (trac\$3 or wir\$3 or pattern))) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | AND | ON | 2009/09/03 18:23 |

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|-----|-----|---|---|-----|----|---------------------|
| S27 | 0 | 439/250.ccls. ((bimetal\$3 or (bi near2 metal \$3)) (thermostat \$3 or switch) relay ((PCB or board or substrate) with (trac\$3 or wir\$3 or pattern))) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | AND | ON | 2009/09/03 18:23 |
| S28 | 0 | 439/620.33.ccls. ((bimetal\$3 or (bi near2 metal \$3)) (thermostat \$3 or switch) relay ((PCB or board or substrate) with (trac\$3 or wir\$3 or pattern))) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | AND | ON | 2009/09/03 18:23 |
| S29 | 0 | 439/620.34.ccls. ((bimetal\$3 or (bi near2 metal \$3)) (thermostat \$3 or switch) relay ((PCB or board or substrate) with (trac\$3 or wir\$3 or pattern))) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | AND | ON | 2009/09/03 18:24 |
| S30 | 3 | "439"/\$.ccls. ((bimetal\$3 or (bi near2 metal \$3)) (thermostat \$3 or switch) relay ((PCB or board or substrate) with (trac\$3 or wir\$3 or pattern))) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | AND | ON | 2009/09/03 18:24 |
| S31 | 252 | S21 relay | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | AND | ON | 2009/09/03 18:24 |

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|-----|----|---|---|-----|----|---------------------|
| S32 | 51 | S31 (foot or feet) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | AND | ON | 2009/09/03 18:24 |
| S33 | 57 | ("1809305" "2759066" "3234350" "3728659" "4103271" "4492946" "4533894" "4567458" "4591820" "4628295" "4646051" "4754251" "4794364" "4842419" "4843364" "4851807" "4887062" "5576683" "5660473" "6597274" "6642460" "6737952" "6833782").PN. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | AND | ON | 2009/09/03 18:27 |
| S55 | 0 | 361/626.ccls. (relay (insulat\$3 near2 plate) contact (bimetal \$3 or (bi near2 metal\$3) or sensitive) (thermostat\$3 or ((thermal or safety) near2 switch)) (PCB or board or substrate)) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | AND | ON | 2009/09/03 18:53 |

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|-----|---|--|---|-----|----|---------------------|
| S56 | 0 | 337/380.ccls. (relay (insulat\$3 near2 plate) contact (bimetal \$3 or (bi near2 metal\$3) or sensitive) (thermostat\$3 or ((thermal or safety) near2 switch)) (PCB or board or substrate)) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | AND | ON | 2009/09/03 18:53 |
| S57 | 0 | 337/381.ccls. (relay (insulat\$3 near2 plate) contact (bimetal \$3 or (bi near2 metal\$3) or sensitive) (thermostat\$3 or ((thermal or safety) near2 switch)) (PCB or board or substrate)) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | AND | ON | 2009/09/03 18:53 |
| S58 | 0 | 337/373.ccls. (relay (insulat\$3 near2 plate) contact (bimetal \$3 or (bi near2 metal\$3) or sensitive) (thermostat\$3 or ((thermal or safety) near2 switch)) (PCB or board or substrate)) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | AND | ON | 2009/09/03 18:53 |

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|-----|---|--|---|-----|----|---------------------|
| S59 | 0 | 337/337.ccls. (relay (insulat\$3 near2 plate) contact (bimetal \$3 or (bi near2 metal\$3) or sensitive) (thermostat\$3 or ((thermal or safety) near2 switch)) (PCB or board or substrate)) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | AND | ON | 2009/09/03 18:53 |
| S60 | 0 | 337/334.ccls. (relay (insulat\$3 near2 plate) contact (bimetal \$3 or (bi near2 metal\$3) or sensitive) (thermostat\$3 or ((thermal or safety) near2 switch)) (PCB or board or substrate)) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | AND | ON | 2009/09/03 18:53 |
| S61 | 0 | "337"/\$.ccls. (relay (insulat\$3 near2 plate) contact (bimetal \$3 or (bi near2 metal\$3) or sensitive) (thermostat\$3 or ((thermal or safety) near2 switch)) (PCB or board or substrate)).clm. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | AND | ON | 2009/09/03 18:53 |

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|-----|---|--|---|-----|----|---------------------|
| S62 | 0 | "361"/\$.ccls. (relay (insulat\$3 near2 plate) contact (bimetal \$3 or (bi near2 metal\$3) or sensitive) (thermostat\$3 or ((thermal or safety) near2 switch)) (PCB or board or substrate)).clm. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | AND | ON | 2009/09/03 18:53 |
| S63 | 0 | "29"/\$.ccls. (relay (insulat\$3 near2 plate) contact (bimetal \$3 or (bi near2 metal\$3) or sensitive) (thermostat\$3 or ((thermal or safety) near2 switch)) (PCB or board or substrate)).clm. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | AND | ON | 2009/09/03 18:53 |
| S64 | 0 | (relay (insulat\$3 near2 plate) contact (bimetal \$3 or (bi near2 metal\$3) or sensitive) (thermostat\$3 or ((thermal or safety) near2 switch)) (PCB or board or substrate)).clm. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | AND | ON | 2009/09/03 18:54 |
| S65 | 3 | ((insulat\$3 near2 plate) contact (bimetal\$3 or (bi near2 metal\$3) or sensitive) (thermostat\$3 or ((thermal or safety) near2 switch)) (PCB or board or substrate)).clm. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | AND | ON | 2009/09/03 18:54 |

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|-----|----|---|---|-----|----|---------------------|
| S68 | 0 | ((insulat\$3 near2 plate) contact (bimetal\$3 or (bi near2 metal\$3) or sensitive) (thermostat\$3 or ((thermal or safety) near2 switch)) ((PCB or board or substrate) with (trac\$3 or wiring or pattern))).clm. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | AND | ON | 2009/09/03 18:55 |
| S69 | 11 | ((insulat\$3 near2 plate) contact (bimetal\$3 or (bi near2 metal\$3) or sensitive) (thermostat\$3 or ((thermal or safety) near2 switch)) ((PCB or board or substrate) with (trac\$3 or wiring or pattern)) relay) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | AND | ON | 2009/09/03 18:55 |
| S70 | 8 | (adriana near2 sartor).in. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | AND | ON | 2009/09/03 18:56 |
| S71 | 23 | elettrotec.as. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | AND | ON | 2009/09/03 18:56 |
| S72 | 0 | (S70 or S71) ((insulat\$3 near2 plate) contact (bimetal\$3 or (bi near2 metal\$3) or sensitive) (thermostat\$3 or ((thermal or safety) near2 switch)) ((PCB or board or substrate) with (trac\$3 or wiring | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | AND | ON | 2009/09/03 18:56 |

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| | | or pattern)) relay).clm. | | | | |
| S73 | 0 | (S70 or S71) ((insulat\$3 near2 plate) contact (bimetal\$3 or (bi near2 metal\$3) or sensitive) (thermostat\$3 or ((thermal or safety) near2 switch)) (PCB or board or substrate) (trac \$3 or wiring or pattern)).clm. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | AND | ON | 2009/09/03 18:56 |
| S74 | 0 | (S70 or S71) ((insulat\$3 near2 plate) contact (bimetal\$3 or (bi near2 metal\$3) or sensitive) (thermostat\$3 or ((thermal or safety) near2 switch)) (PCB or board or substrate) (trac \$3 or wiring or pattern)) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | AND | ON | 2009/09/03 18:56 |
| S75 | 0 | 337/381.ccls. ((insulat\$3 near2 plate) contact (bimetal\$3 or (bi near2 metal\$3) or sensitive) (thermostat\$3 or ((thermal or safety) near2 switch)) (PCB or board or substrate) (trac \$3 or wiring or pattern)) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | AND | ON | 2009/09/03 18:57 |

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|-----|---|--|---|-----|----|---------------------|
| S76 | 1 | 337/380.ccls. ((insulat\$3 near2 plate) contact (bimetal\$3 or (bi near2 metal\$3) or sensitive) (thermostat\$3 or ((thermal or safety) near2 switch)) (PCB or board or substrate) (trac \$3 or wiring or pattern)) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | AND | ON | 2009/09/03 18:57 |
| S77 | 0 | 337/373.ccls. ((insulat\$3 near2 plate) contact (bimetal\$3 or (bi near2 metal\$3) or sensitive) (thermostat\$3 or ((thermal or safety) near2 switch)) (PCB or board or substrate) (trac \$3 or wiring or pattern)) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | AND | ON | 2009/09/03 18:57 |
| S79 | 0 | 337/334.ccls. ((insulat\$3 near2 plate) contact (bimetal\$3 or (bi near2 metal\$3) or sensitive) (thermostat\$3 or ((thermal or safety) near2 switch)) (PCB or board or substrate) (trac \$3 or wiring or pattern)) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | AND | ON | 2009/09/03 18:58 |

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| S80 | 0 | 337/337.ccls. ((insulat\$3 near2 plate) contact (bimetal\$3 or (bi near2 metal\$3) or sensitive) (thermostat\$3 or ((thermal or safety) near2 switch)) (PCB or board or substrate) (trac \$3 or wiring or pattern)) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | AND | ON | 2009/09/03 18:58 |
| S81 | 63 | ((insulat\$3 near2 plate) contact (bimetal\$3 or (bi near2 metal\$3) or sensitive) (thermostat\$3 or ((thermal or safety) near2 switch)) (PCB or board or substrate) (trac \$3 or wiring or pattern)) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | AND | ON | 2009/09/03 18:58 |
| S82 | 4294 | ((bimetal\$3 or (bi near2 metal \$3) or sensitive) (thermostat\$3 or ((thermal or safety) near2 switch)) (PCB or board or substrate) (trac \$3 or wiring or pattern)) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | AND | ON | 2009/09/03 18:59 |
| S83 | 1371 | S82 ((hous\$3 or cas\$3 or support) with (contact or lead or terminal)) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | AND | ON | 2009/09/03 18:59 |
| S84 | 401 | S83 relay | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | AND | ON | 2009/09/03 18:59 |

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|-----|------|---|---|-----|----|---------------------|
| S85 | 4294 | ((bimetal\$3 or (bi near2 metal \$3) or sensitive) (thermostat\$3 or ((thermal or safety) near2 switch)) (PCB or board or substrate) (trac \$3 or wiring or pattern)) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | AND | ON | 2009/09/03 19:00 |
| S86 | 320 | S85 (cover with (contact or lead or terminal)) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | AND | ON | 2009/09/03 19:00 |
| S87 | 29 | S86 ((base or bottom) with (pack\$3 or pierc \$3)) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | AND | ON | 2009/09/03 19:01 |

EAST Search History (Interference)

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|------|---------------|-----------------------------|------------------|---------|------------------|
| S34 | 108 | 361/626.ccls. | US-PGPUB; USPAT; UPAD | AND | ON | 2009/09/03 18:30 |
| S35 | 176 | 337/333.ccls. | US-PGPUB; USPAT; UPAD | AND | ON | 2009/09/03 18:31 |
| S36 | 453 | 337/380.ccls. | US-PGPUB; USPAT; UPAD | AND | ON | 2009/09/03 18:31 |
| S37 | 226 | 337/373.ccls. | US-PGPUB; USPAT; UPAD | AND | ON | 2009/09/03 18:39 |
| S38 | 160 | 337/381.ccls. | US-PGPUB; USPAT; UPAD | AND | ON | 2009/09/03 18:41 |
| S39 | 58 | 337/334.ccls. | US-PGPUB; USPAT; UPAD | AND | ON | 2009/09/03 18:44 |

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| S40 | 54 | 337/337.ccls. | US-PGPUB; USPAT; UPAD | AND | ON | 2009/09/03 18:44 |
| S41 | 1128 | (S34 or S35 or S36 or S37 or S38 or S39 or S40) | US-PGPUB; USPAT; UPAD | AND | ON | 2009/09/03 18:45 |
| S42 | 2 | S41 (contact (bimetal\$3 or (bi near2 metal\$3)) (thermostat\$3 or switch) relay ((PCB or board or substrate) with (trac\$3 or wir\$3 or pattern))) | US-PGPUB; USPAT; UPAD | AND | ON | 2009/09/03 18:45 |
| S43 | 0 | S41 (contact (bimetal\$3 or (bi near2 metal\$3)) (thermostat\$3 or switch) relay ((PCB or board or substrate) with (trac\$3 or wir\$3 or pattern))).clm. | US-PGPUB; USPAT; UPAD | AND | ON | 2009/09/03 18:45 |
| S44 | 37 | S41 (contact (bimetal\$3 or (bi near2 metal\$3)) (thermostat\$3 or switch) (PCB or board or substrate)) | US-PGPUB; USPAT; UPAD | AND | ON | 2009/09/03 18:47 |
| S45 | 8 | S41 (contact (bimetal\$3 or (bi near2 metal\$3)) (thermostat\$3 or switch) (PCB or board or substrate)).clm. | US-PGPUB; USPAT; UPAD | AND | ON | 2009/09/03 18:48 |
| S46 | 5 | S41 (relay (bimetal \$3 or (bi near2 metal\$3) or sensitive) (thermostat\$3 or ((thermal or safety) near2 switch)) (PCB or board or substrate)) | US-PGPUB; USPAT; UPAD | AND | ON | 2009/09/03 18:49 |

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| S47 | 0 | S41 (relay (bimetal \$3 or (bi near2 metal\$3) or sensitive) (thermostat\$3 or ((thermal or safety) near2 switch)) (PCB or board or substrate)).clm. | US-PGPUB; USPAT; UPAD | AND | ON | 2009/09/03 18:49 |
| S48 | 35 | "337"/\$.ccls. (relay (bimetal\$3 or (bi near2 metal \$3) or sensitive) (thermostat\$3 or ((thermal or safety) near2 switch)) (PCB or board or substrate)) | US-PGPUB; USPAT; UPAD | AND | ON | 2009/09/03 18:49 |
| S49 | 309 | 29/623.ccls. | US-PGPUB; USPAT; UPAD | AND | ON | 2009/09/03 18:50 |
| S50 | 0 | S49 (relay (bimetal \$3 or (bi near2 metal\$3) or sensitive) (thermostat\$3 or ((thermal or safety) near2 switch)) (PCB or board or substrate)) | US-PGPUB; USPAT; UPAD | AND | ON | 2009/09/03 18:50 |
| S51 | 0 | S49 (relay (bimetal \$3 or (bi near2 metal\$3) or sensitive) (thermostat\$3 or ((thermal or safety) near2 switch)) (PCB or board or substrate)).clm. | US-PGPUB; USPAT; UPAD | AND | ON | 2009/09/03 18:50 |

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|-----|---|--|-----------------------------|-----|----|------------------|
| S52 | 1 | "361"/\$.ccls. (relay (bimetal\$3 or (bi near2 metal \$3) or sensitive) (thermostat\$3 or ((thermal or safety) near2 switch)) (PCB or board or substrate)).clm. | US-PGPUB; USPAT; UPAD | AND | ON | 2009/09/03 18:51 |
| S53 | 0 | "361"/\$.ccls. (relay (insualt\$3 near2 plate) contact (bimetal \$3 or (bi near2 metal\$3) or sensitive) (thermostat\$3 or ((thermal or safety) near2 switch)) (PCB or board or substrate)).clm. | US-PGPUB; USPAT; UPAD | AND | ON | 2009/09/03 18:52 |
| S54 | 0 | "337"/\$.ccls. (relay (insualt\$3 near2 plate) contact (bimetal \$3 or (bi near2 metal\$3) or sensitive) (thermostat\$3 or ((thermal or safety) near2 switch)) (PCB or board or substrate)).clm. | US-PGPUB; USPAT; UPAD | AND | ON | 2009/09/03 18:52 |
| S66 | 0 | "337"/\$.ccls. (relay (insulat\$3 near2 plate) contact (bimetal \$3 or (bi near2 metal\$3) or sensitive) (thermostat\$3 or ((thermal or safety) near2 switch)) (PCB or board or substrate)).clm. | US-PGPUB; USPAT; UPAD | AND | ON | 2009/09/03 18:52 |

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|-----|---|--|-----------------------------|-----|----|------------------|
| S67 | 0 | "361"/\$.ccls. (relay (insulat\$3 near2 plate) contact (bimetal \$3 or (bi near2 metal\$3) or sensitive) (thermostat\$3 or ((thermal or safety) near2 switch)) (PCB or board or substrate)).clm. | US-PGPUB; USPAT; UPAD | AND | ON | 2009/09/03 18:52 |
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